

Description

The 9ZXL0651 is a low-power 6-output differential buffer that meets all the performance requirements of the Intel DB1200Z specification. It consumes 50% less power than standard HCSL devices and has internal terminations to allow direct connection to 85Ω transmission lines. It is suitable for PCI-Express Gen1/2/3 or QPI/UPI applications, and uses a fixed external feedback to maintain low drift for demanding QPI/UPI applications.

Applications

Buffer for Romley, Grantley and Purley Servers, SSDs and PCle

Output Features

 6 – LP-HCSL Output Pairs w/integrated terminations (Zo = 85Ω)

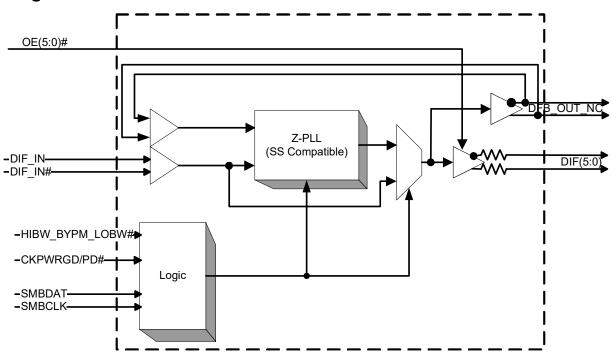
Features

- 25MHz PFT clock delay management
- Low-Power-HCSL outputs with Zo = 85Ω ; save power and board space no termination resistors required. Ideal for blade servers.
- Space-saving 40-pin VFQFPN package
- · Fixed feedback path for 0ps input-to-output delay
- 6 OE# pins; hardware control of each output
- PLL or bypass mode; PLL can dejitter incoming clock
- Selectable PLL bandwidth; minimizes jitter peaking in downstream PLLs
- Spread spectrum compatible; tracks spreading input clock for low EMI

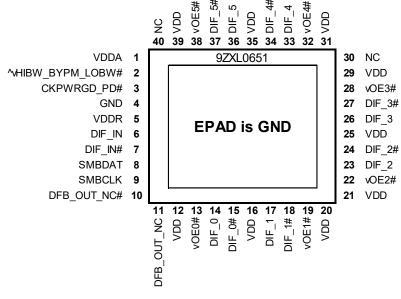
Key Specifications

- Cycle-to-cycle jitter < 50ps
- Output-to-output skew < 65ps
- Input-to-output delay variation < 50ps
- PCIe Gen3 phase jitter < 1.0ps RMS
- QPI/UPI 9.6GT/s 12UI phase jitter < 0.2ps RMS

Block Diagram



Pin Configuration



40-VFQFPN

^ prefix indicates internal Pull-Up Resistor v prefix indicates Internal Pull-Dow n Resistor ^v prefix indicates Internal Pull-Up/Dow n Resistor (biased to VDD/2)

5mm x 5mm 0.4mm pin pitch

Power Management Table

CKPWRGD_PD#	DIF_IN/ DIF_IN#	SMBus EN bit	DIF(5:0)/ DIF(5:0)#	PLL STATE IF NOT IN BYPASS MODE
0	Х	Х	Low/Low	OFF
4	Dunning	0	Low/Low	ON
l l	Running	1	Running	ON

PLL Operating Mode

HiBW_BypM_LoBW#	MODE
Low	PLL Lo BW
Mid	Bypass
Hiah	PLL Hi BW

NOTE: PLL is OFF in Bypass Mode

Power Connections

Pin N	umber	
VDD	GND	Description
1	41	Analog PLL
5	4	Analog Input
12,16,20,24,27 ,31,32,36,40	41	DIF clocks

PLL Operating Mode Readback Table

HiBW_BypM_LoBW#	Byte0, bit 7	Byte 0, bit 6
Low (Low BW)	0	0
Mid (Bypass)	0	1
High (High BW)	1	1

Tri-level Input Thresholds

Level	Voltage
Low	<0.8V
Mid	1.2 <vin<1.8v< th=""></vin<1.8v<>
High	Vin > 2.2V

9ZXL0651 SMBus Address

1101100	+ Read/Write bit



Pin Descriptions

Sexit Power Down Mode on subsequent	ails. ched inputs and start up on first high assertion, or assertions. Low enters Power Down Mode. receiver). This VDD should be treated as an
2 NOR DIN See PLL Operating Mode Table for Deta 3 CKPWRGD_PD# Trays 3.3V Input notifies device to sample lat exit Power Down Mode on subsequent 4 GND Ground pin. 5 VDDR PWR 3.3V power for differential input clock (ranalog power rail and filtered appropriat 6 DIF_IN IN 0.7 V Differential True input	ails. ched inputs and start up on first high assertion, or assertions. Low enters Power Down Mode. receiver). This VDD should be treated as an
exit Power Down Mode on subsequent 4 GND GND Ground pin. 5 VDDR PWR 3.3V power for differential input clock (ranalog power rail and filtered appropriat 6 DIF_IN IN 0.7 V Differential True input	assertions. Low enters Power Down Mode. receiver). This VDD should be treated as an
5 VDDR PWR 3.3V power for differential input clock (ranalog power rail and filtered appropriat 6 DIF_IN IN 0.7 V Differential True input	· ·
5 VDDR analog power rail and filtered appropriat 6 DIF_IN IN 0.7 V Differential True input	·
7 DIF_IN# IN 0.7 V Differential Complementary Input	
8 SMBDAT I/O Data pin of SMBUS circuitry, 5V toleral	nt
9 SMBCLK IN Clock pin of SMBUS circuitry, 5V tolera	
10 DFB_OUT_NC# OUT for synchronization with input clock to e connected on the circuit board, the feed	
11 DFB_OUT_NC OUT synchronization with the input clock to connected on the circuit board, the feed	r, provides feedback signal to the PLL for eliminate phase error. This pin should NOT be dback is internal to the package.
12 VDD PWR Power supply, nominal 3.3V	
13 vOE0# IN Active low input for enabling DIF pair 0. 1 = disable outputs, 0 = enable outputs	
14 DIF_0 OUT 0.7V differential true clock output	
15 DIF_0# OUT 0.7V differential Complementary clock	output
16 VDD PWR Power supply, nominal 3.3V	
17 DIF_1 OUT 0.7V differential true clock output	
18 DIF_1# OUT 0.7V differential Complementary clock	output
19 vOE1# IN Active low input for enabling DIF pair 1. 1 = disable outputs, 0 = enable outputs	
20 VDD PWR Power supply, nominal 3.3V	
21 VDD PWR Power supply, nominal 3.3V	
22 vOE2# IN Active low input for enabling DIF pair 2. 1 = disable outputs, 0 = enable outputs	
23 DIF 2 OUT 0.7V differential true clock output	
24 DIF 2# OUT 0.7V differential Complementary clock	output
25 VDD PWR Power supply, nominal 3.3V	
26 DIF_3 OUT 0.7V differential true clock output	
27 DIF_3# OUT 0.7V differential Complementary clock	output
28 vOE3# IN Active low input for enabling DIF pair 3. 1 = disable outputs, 0 = enable outputs	
29 VDD PWR Power supply, nominal 3.3V	
30 NC N/A No Connection.	
31 VDD PWR Power supply, nominal 3.3V	
32 vOE4# IN Active low input for enabling DIF pair 4. 1 = disable outputs, 0 = enable outputs	
33 DIF_4 OUT 0.7V differential true clock output	
34 DIF 4# OUT 0.7V differential Complementary clock	output
35 VDD PWR Power supply, nominal 3.3V	
36 DIF_5 OUT 0.7V differential true clock output	
37 DIF_5# OUT 0.7V differential Complementary clock	output
38 vOE5# IN Active low input for enabling DIF pair 5. 1 =disable outputs, 0 = enable outputs	This pin has an internal pull-down.
39 VDD PWR Power supply, nominal 3.3V	
40 NC N/A No Connection.	
41 EPAD GND Ground Pad.	



Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 9ZXL0651. These ratings, which are standard values for Renesas commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
	VDD, VDDA,						
3.3V Core Supply Voltage	VDDR	VDD for core logic and PLL			4.6	V	1,2
Input Low Voltage	V_{IL}		GND-0.5			V	1
Input High Voltage	V _{IH}	Except for SMBus interface			V _{DD} +0.5V	V	1
Input High Voltage	V _{IHSMB}	SMBus clock and data pins			5.5V	٧	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics-DIF_IN Clock Input Parameters

 $T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3 \text{ V +/-5}\%$

			1				
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Input Crossover Voltage - DIF_IN	V _{CROSS}	Crossover Voltage	150		900	mV	1
Input Swing - DIF_IN	V_{SWING}	Differential value	300			mV	1
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2
Input Leakage Current	I _{IN}	$V_{IN} = V_{DD}$, $V_{IN} = GND$	-5		5	uA	
Input Duty Cycle	d_{tin}	Measurement from differential waveform	45		55	%	1
Input Jitter - Cycle to Cycle	J_{DIFIn}	Differential Measurement	0		125	ps	1

¹ Guaranteed by design and characterization, not 100% tested in production.

² Operation under these conditions is neither implied nor guaranteed.

 $^{^{2}}$ Slew rate measured through +/-75mV window centered around differential zero.



Electrical Characteristics-Input/Supply/Common Parameters

 $T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3 V + -5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	T _{COM}	Commercial range	0	35	70	°C	1
Input High Voltage	V_{IH}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V _{DD} + 0.3	V	1
Input Low Voltage	V _{IL}	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	V	1
	I _{IN}	Single-ended inputs, V_{IN} = GND, V_{IN} = VDD	-5		5	uA	1
Input Current	I _{INP}	$\label{eq:single-ended} Single-ended inputs \\ V_{IN} = 0 \ V; \ Inputs \ with internal \ pull-up \ resistors \\ V_{IN} = \ VDD; \ Inputs \ with \ internal \ pull-down \ resistors \\$	-200		200	uA	1
Input Frequency	F_{ibyp}	V _{DD} = 3.3 V, Bypass mode	25		150	MHz	2
input Frequency	F _{ipll}	V _{DD} = 3.3 V, 100MHz PLL mode	25	100.00	110	MHz	2
Pin Inductance	L _{pin}				7	nH	1
	C _{IN}	Logic Inputs, except DIF_IN	1.5		5	pF	1
Capacitance	C _{INDIF_IN}	DIF_IN differential clock inputs	1.5		2.7	pF	1,4
	C _{OUT}	Output pin capacitance			6	pF	1
Clk Stabilization	T _{STAB}	From V _{DD} Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.53	1	ms	1,2
Input SS Modulation Frequency	f _{MODIN}	Allowable Frequency (Triangular Modulation)	30		33	kHz	1
OE# Latency	t _{LATOE#}	DIF start after OE# assertion DIF stop after OE# deassertion	4	8	12	cycles	1,3
Tdrive_PD#	t _{DRVPD}	DIF output enable after PD# de-assertion			300	us	1,3
Tfall	t_{F}	Fall time of control inputs			10	ns	1,2
Trise	t_R	Rise time of control inputs			10	ns	1,2
SMBus Input Low Voltage	V_{ILSMB}				0.8	V	1
SMBus Input High Voltage	V_{IHSMB}		2.1		V _{DDSMB}	V	1
SMBus Output Low Voltage	V_{OLSMB}	At I _{PULLUP}			0.4	V	1
SMBus Sink Current	I _{PULLUP}	At V _{OL}	4			mA	1
Nominal Bus Voltage	V_{DDSMB}	3V to 5V +/- 10%	2.7		5.5	V	1
SCLK/SDATA Rise Time	t _{RSMB}	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t _{FSMB}	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f _{MAXSMB}	Maximum SMBus operating frequency			100	kHz	1,5

¹ Guaranteed by design and characterization, not 100% tested in production.

 $^{^{2}\,\}mbox{Control}$ input must be monotonic from 20% to 80% of input swing.

 $^{^3}$ Time from deassertion until outputs are > 200mV.

⁴ DIF_IN input.

 $^{^{\}rm 5}$ The differential input clock must be running for the SMBus to be active.



Electrical Characteristics-DIF 0.7V Low Power HCSL Outputs

 $T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3 \text{ V +/-5}\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on	1	2.9	4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching, Scope averaging on		7	20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope	660	754	850	mV	1
Voltage Low	VLow	averaging on)	-150	62	150] '''V	1
Max Voltage	Vmax	Measurement on single ended signal using		827	1150	mV	1
Min Voltage	Vmin	absolute value. (Scope averaging off)	-300	10		IIIV	1
Vswing	Vswing	Scope averaging off	300	1395		mV	1, 2
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	300	453	550	mV	1, 5
Crossing Voltage (var)	Δ-Vcross	Scope averaging off		14	140	mV	1, 6

 $^{^{1}}$ Guaranteed by design and characterization, not 100% tested in production. C_L = 2pF, Zo = 85 Ω differential trace impedance).

Electrical Characteristics-Current Consumption

 $T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3 V + /-5\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
	I _{DDVDDR}	100MHz, VDDR rail		4	6	mA	1
Operating Current	I _{DDVDDAPLL}	100MHz, VDDA rail, PLL Mode		14	20	mA	1
Operating Current	I _{DDVDDABYP}	100MHz, VDDA rail, Bypass Mode		3	5	mA	1
	I _{DDVDD}	100MHz, VDD rail		41	50	mA	1
	I _{DDVDDRPD}	Power Down, VDDR Rail		3.5	5	mA	1
Powerdown Current	I _{DDVDDAPD}	Power Down, VDDA Rail		1.6	3	mA	1
	I _{DDVDDPD}	Power Down, VDD Rail		0.3	2	20 mA 5 mA 50 mA 55 mA	1

¹Guaranteed by design and characterization, not 100% tested in production.

² Measured from differential waveform

³ Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

⁴ Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

⁵ Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

⁶ The total variation of all Vcross measurements in any particular system. Note that this is a subset of Vcross_min/max (Vcross absolute) allowed. The intent is to limit Vcross induced modulation by setting Δ-Vcross to be smaller than Vcross absolute.

 $^{^{2}}$ C_L = 2pF, Zo = 85 Ω differential trace impedance



Electrical Characteristics-Skew and Differential Jitter Parameters

 $T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3 \text{ V +/-5}\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
CLK_IN, DIF[x:0]	t _{SPO_PLL}	In-to-Out Skew in PLL mode @ 100MHz nominal value @35°C, 3.3V	-100	53	100	ps	1,2,4,5,8
CLK_IN, DIF[x:0]	t _{PD_BYP}	In-to-Out Skew in Bypass mode @ 100MHz nominal value @ 35°C, 3.3V	2.5	3.4	4.5	ns	1,2,3,5,8
CLK_IN, DIF[x:0]	t _{DSPO_PLL}	In-to-Out Skew Variation in PLL mode across voltage and temperature	-50	0	50	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t _{DSPO_BYP}	In-to-Out Skew Variation in Bypass mode across voltage and temperature	-250	0	250	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t _{DTE}	Random Differential Tracking error between two 9ZX devices in Hi BW Mode		3	5	ps (rms)	1,2,3,5,8
CLK_IN, DIF[x:0]	t _{DSSTE}	Random Differential Spread Spectrum Tracking error between two 9ZX devices in Hi BW Mode		15	75	ps	1,2,3,5,8
DIF{x:0]	t _{SKEW_ALL}	Output-to-Output Skew across all outputs (Common to Bypass and PLL mode)		39	65	ps	1,2,3,8
PLL Jitter Peaking	jpeak-hibw	LOBW#_BYPASS_HIBW = 1			2.5	dB	7,8
PLL Jitter Peaking	jpeak-lobw	LOBW#_BYPASS_HIBW = 0			2	dB	7,8
PLL Bandwidth	pll _{HIBW}	LOBW#_BYPASS_HIBW = 1			4	MHz	8,9
PLL Bandwidth	pll _{LOBW}	LOBW#_BYPASS_HIBW = 0			1.4	MHz	8,9
Duty Cycle	t _{DC}	Measured differentially, PLL Mode	45	50.1	55	%	1
Duty Cycle Distortion	t _{DCD}	Measured differentially, Bypass Mode @100MHz		-1.7	2	%	1,10
Jitter, Cycle to cycle	t _{jcyc-cyc}	PLL mode		14	50	ps	1,11
Notes for a second to eyele	gcy c-cy c	Additive Jitter in Bypass Mode		0	25	ps	1,11

Notes for preceding table:

¹ C_L = 2pF, Zo = 85Ω differential trace impedance. Input to output skew is measured at the first output edge following the corresponding input.

² Measured from differential cross-point to differential cross-point. This parameter can be tuned with external feedback path, if present.

³ All Bypass Mode Input-to-Output specs refer to the timing between an input edge and the specific output edge created by it.

⁴ This parameter is deterministic for a given device

⁵ Measured with scope averaging on to find mean value.

⁶ t is the period of the input clock

⁷ Measured as maximum pass band gain. At frequencies within the loop BW, highest point of magnification is called PLL jitter peaking.

^{8.} Guaranteed by design and characterization, not 100% tested in production.

⁹ Measured at 3 db down or half power point.

¹⁰ Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

¹¹ Measured from differential waveform



Electrical Characteristics-Phase Jitter Parameters

 $T_A = T_{COM}$; Supply Voltage $V_{DD} = 3.3 \text{ V +/-5}\%$

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	INDUSTRY LIMIT	UNITS	Notes
	t _{jphPCleG1}	PCIe Gen 1		43	46	86	ps (p-p)	1,2,3
		PCle Gen 2 Lo Band 10kHz < f < 1.5MHz		1.4	1.5	3	ps (rms)	1,2
	t _{jphPCIeG2}	PCle Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.4	2.7	3.1	ps (rms)	1,2
	t _{jphPCIeG3}	PCIe Gen 3 (PLL BW of 2-4MHz, 2-5MHz, CDR = 10MHz)		0.56	0.61	1	ps (rms)	1,2,4
Phase Jitter, PLL Mode		QPI & SMI (PLL BW of 17.04MHz 100/133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.27	0.51	1	ps (rms)	1,5
	t _{jphQPI_SMI}	QPI & SMI (PLL BW of 7.8MHz 100/133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.22	0.49	0.5	ps (rms)	1,5
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.16	0.28	0.3	ps (rms)	1,5
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.11	0.17	0.2	ps (rms)	1,5
	t _{jphPCleG1}	PCle Gen 1		1	5	N/A	ps (p-p)	1,2,3
	t _{iphPCIeG2}	PCle Gen 2 Lo Band 10kHz < f < 1.5MHz		0.0	0.0	N/A	ps (rms)	1,2,6
	gpnPCTeG2	PCle Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.0	0.0	N/A	ps (rms)	1,2,6
	t _{jphPCIeG3}	PCle Gen 3 (PLL BW of 2-4MHz, 2-5MHz, CDR = 10MHz)		0.0	0.0	N/A	ps (rms)	1,2,4,6
Additive Phase Jitter, Bypass mode		QPI & SMI (PLL BW of 17.04MHz 100/133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.25	0.3	N/A	ps (rms)	1,5,6
	t _{jphQPI_SMI}	QPI & SMI (PLL BW of 7.8MHz 100/133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.10	0.15	N/A	ps (rms)	1,5,6
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.0	0.0	N/A	ps (rms)	1,5,6
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.0	0.0	N/A	ps (rms)	1,5,6

¹ Applies to all outputs.

 $^{^2\,\}mbox{See}$ http://www.pcisig.com for complete specs.

³ Sample size of at least 100K cycles. This figure extrapolates to 108ps pk-pk at 1M cycles for a BER of 1⁻¹².

⁴ Subject to final ratification by PCI SIG.

⁵ Calculated from Intel-supplied clock jitter tool.

⁶ For RMS figures, additive jitter is calculated by solving the following equation: (Additive jitter)² = (total jitter)² - (input jitter)².



Clock Periods-Differential Outputs with Spread Spectrum Disabled

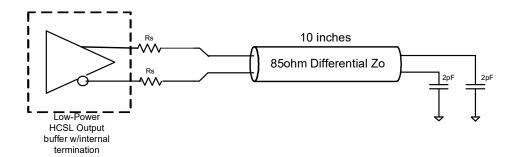
			Measurement Window							
	Center	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
SSC OFF	Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
DIF	100.00	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2,3

Clock Periods-Differential Outputs with Spread Spectrum Enabled

Conto		Measurement Window								
	Contor	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
SSC ON	Center Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
DIF	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2,3

Notes

Test Loads



Differential Output Terminations

DIF Zo (Ω)	Rs (Ω)
100	7
85	0

Note: No resistors are required for connection to 85ohm transmission lines.

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK420BQ/CK410B+ accuracy requirements (+/-100ppm). The 9ZXL0651 itself does not contribute to ppm error.

³ Driven by SRC output of main clock, 100 MHz PLL Mode or Bypass mode

General SMBus Serial Interface Information for 9ZXL0651

How to Write

- · Controller (host) sends a start bit
- · Controller (host) sends the write address
- Renesas clock will acknowledge
- Controller (host) sends the beginning byte location = N
- Renesas clock will acknowledge
- Controller (host) sends the byte count = X
- Renesas clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- Renesas clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

	Index BI	ock '	Write Operation
Controll	er (Host)		Renesas (Slave/Receiver)
Т	starT bit		
Slave A	Address		
WR	WRite		
			ACK
Beginning	Byte = N		
			ACK
Data Byte	Count = X		
			ACK
Beginnin	g Byte N		
			ACK
0		×	
0		X Byte	0
0		(Đ	0
			0
Byte N	+ X - 1		
			ACK
Р	stoP bit		

How to Read

- Controller (host) will send a start bit
- · Controller (host) sends the write address
- Renesas clock will acknowledge
- Controller (host) sends the beginning byte location = N
- Renesas clock will acknowledge
- · Controller (host) will send a separate start bit
- · Controller (host) sends the read address
- Renesas clock will acknowledge
- Renesas clock will send the data byte count = X
- Renesas clock sends Byte N+X-1
- Renesas clock sends Byte 0 through Byte X (if X_(H) was written to Byte 8)
- · Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- · Controller (host) will send a stop bit

	Index Block F	Read O	peration
Cor	ntroller (Host)		Renesas
Т	starT bit		
SI	ave Address		
WR	WRite		
			ACK
Begi	nning Byte = N		
			ACK
RT	Repeat starT		
SI	ave Address		
RD	ReaD		
			ACK
			Data Byte Count=X
	ACK		
			Beginning Byte N
	ACK		
		த	0
	0	X Byte	0
	0	×	0
	0		
			Byte N + X - 1
N	Not acknowledge		
Р	stoP bit		



SMBusTable: PLL Mode, and Frequency Select Register

Byte	0 Pin#	Name	Control Function	Type	0	1	Default	
Bit 7	2	PLL Mode 1	PLL Operating Mode Rd back 1	R	See PLL Op	See PLL Operating Mode		
Bit 6	2	PLL Mode 0	PLL Operating Mode Rd back 0	R	Readba	Latch		
Bit 5			Reserved				0	
Bit 4			Reserved					
Bit 3		PLL_SW_EN	Enable S/W control of PLL BW	RW	HW Latch	SMBus Control	0	
Bit 2		PLL Mode 1	PLL Operating Mode 1	RW	See PLL Op	erating Mode	1	
Bit 1		PLL Mode 0	PLL Operating Mode 1	RW	Readba	ck Table	1	
Bit 0			Reserved					

Note: Setting bit 3 to '1' allows the user to override the Latch value from pin 5 via use of bits 2 and 1. Use the values from the PLL Operating Mode Readback Table. Note that Bits 7 and 6 will keep the value originally latched on pin 5. A warm reset of the system will have to accomplished if the user changes these bits.

SMBusTable: Output Control Register

Byte	e 1	Pin#	Name	Control Function	Туре	0	1	Default	
Bit 7				Reserved				1	
Bit 6	2	26/27	DIF_3_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1	
Bit 5	2	23/24	DIF_2_En	Output Control - '0' overrides OE# pin	RW	LOW/LOW	Ellable	1	
Bit 4				Reserved					
Bit 3				Reserved				1	
Bit 2	1	17/18	DIF_1_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1	
Bit 1	1	14/15	DIF_0_En	Output Control - '0' overrides OE# pin	RW	LOW/LOW	Ellable	1	
Bit 0				Reserved				1	

SMBusTable: Output Control Register

Byte	e 2	Pin#	Name	Control Function	Type	0	1	Default		
Bit 7				Reserved				0		
Bit 6				Reserved						
Bit 5				Reserved						
Bit 4				Reserved						
Bit 3				Reserved				1		
Bit 2	3	6/37	DIF_5_En	Output Control - '0' overrides OE# pin	RW	Low/Low	Enable	1		
Bit 1	3	3/34	DIF_4_En	Output Control - '0' overrides OE# pin	RW	LOW/LOW	Enable	1		
Bit 0				Reserved						

SMBusTable: Reserved Register

Byte	e 3	Pin#	Name	Control Function	Type	0	1	Default		
Bit 7				Reserved				0		
Bit 6				Reserved						
Bit 5				Reserved						
Bit 4			Reserved							
Bit 3				Reserved				0		
Bit 2				Reserved				0		
Bit 1				Reserved				0		
Bit 0				Reserved				0		

SMBusTable: Reserved Register

Byte 4	Pin #	Name	Control Function	Туре	0	1	Default
Bit 7			Reserved				0
Bit 6			Reserved				0
Bit 5			Reserved				0
Bit 4			Reserved				0
Bit 3			Reserved				0
Bit 2			Reserved				0
Bit 1			Reserved				0
Bit 0			Reserved				0



SMBusTable: Vendor & Revision ID Register

Byte !	5 Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	RID3		R		Х	
Bit 6	-	RID2	REVISION ID	R	A rev	X	
Bit 5	-	RID1		R	A IEV	X	
Bit 4	-	RID0		R		X	
Bit 3	-	VID3		R	-	-	0
Bit 2	-	VID2	VENDOR ID	R	-	-	0
Bit 1	-	VID1	VENDOR ID	R	-	-	0
Bit 0	-	VID0		R	-	-	1

SMBusTable: DEVICE ID

Byte 6 Pin #		Name Control Function		Type	0	1	Default
Bit 7		De	evice ID 7 (MSB)	R	₹		
Bit 6			Device ID 6	R		1	
Bit 5			Device ID 5	R			1
Bit 4			Device ID 4	R	гв	Hex	1
Bit 3			Device ID 3	R	ГБ	пех	1
Bit 2	-		Device ID 2	R			0
Bit 1			Device ID 1	R		1	
Bit 0	-		Device ID 0	R			1

SMBusTable: Byte Count Register

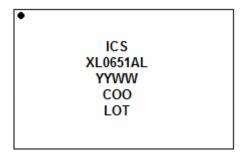
Byte 7	Pin #	Name	Control Function	Type	0	1	Default		
Bit 7			Reserved						
Bit 6			Reserved						
Bit 5			Reserved						
Bit 4	-	BC4		RW			0		
Bit 3	-	BC3	Writing to this register configures how	RW	Default value	1			
Bit 2	-	BC2		RW	bytes (0 to 8) v	0			
Bit 1	-	BC1	many bytes will be read back.	RW	by de	0			
Bit 0	-	BC0		RW] '		0		

SMBusTable: Reserved Register

Byte 8 Pin # Name		Name	Control Function	Type	0	1	Default	
Bit 7			Reserved				0	
Bit 6			Reserved	served				
Bit 5		Reserved					0	
Bit 4		Reserved					0	
Bit 3		Reserved					0	
Bit 2			Reserved				0	
Bit 1		Reserved					0	
Bit 0			Reserved				0	



Marking Diagram



- · Line 2: truncated part number; "L" denotes RoHS compliant package.
- Line 3: "YYWW" is the last two digits of the year and week that the part was assembled.
- Line 4: "COO": country of origin.
- Line 5: "LOT" denotes the lot number.

Package Outline Drawings

The package outline drawings are appended at the end of this document. The package information is the most current data available.

Ordering Information

Part / Order Number		Shipping Package	Package	Temperature	
9ZXL0651AKLF		Trays	40-pin VFQFPN	0 to +70°C	
9ZXL0	551AKLFT	Tape and Reel	40-pin VFQFPN	0 to +70°C	

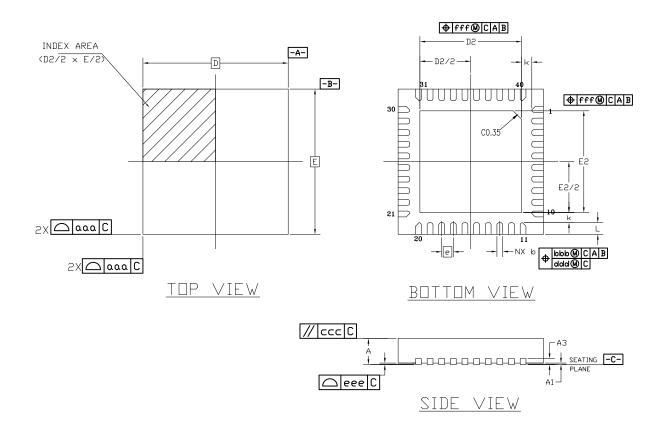
[&]quot;LF" suffix to the part number denotes Pb-Free configuration, RoHS compliant.

Revision History

Revision Date	Description				
October 31, 2013 Updated Electrical Tables with characterization data and moved to final.					
November 25, 2014	1. Updates to Byte 6, bits 7:4; default should be "1".				
November 25, 2014	2. Updated device ID in Byte 6 from "8B" to "FB".				
March 30, 2015	1. Corrected Test Loads to remove references to IREF and Rp. These are not present on parts				
Walcii 30, 2013	that have LP-HCSL outputs.				
November 20, 2015	1. Updated QPI references to QPI/UPI				
November 20, 2013	2. Updated DIF_IN table to match PCI SIG specification, no silicon change				
	1. Updated input frequency minimum values from 33MHz to 25MHz.				
January 28, 2021	2. Added "25MHz PFT clock delay management" bullet to Features section on cover page.				
January 20, 2021	3. Reformatted headers and footers to Renesas.				
	4. Updated Marking Diagram and Package Outline Drawings sections.				

[&]quot;A" is the device revision designator (will not correlate with the datasheet revision).

	REVISIONS						
REV	DESCRIPTION	DATE	APPROVED				
00	INITIAL RELEASE	5/17/16	JH				



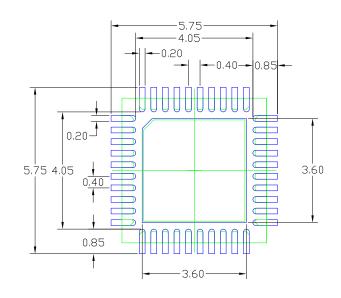
SYMBOL	DIMENSION					
P	MIN	NOM	MAX			
b	0.15	0.20	0.25			
D	5	.00 BSC				
Е	5	.00 BSC				
D2	3.40	3.50	3.60			
E2	3.40	3.50	3.60			
L	0.30	0.40	0.50			
е	C	.40 BSC				
N		40				
ND			ote 3)			
NE		10 (n	ote 3)			
Α	0.80	0.90	1.00			
A1	0.00	0.02	0.05			
A3		0.2 REF				
k		0.35 RE	F			
aaa	0.10					
bbb		0.07				
ccc	0.10					
ddd	0.05					
eee		0.08				
fff		0.10				

NOTES:

- 1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- 3. ND AND NE REFER TO THE NUMBER OF TERMINALS ON EACH D AND E SIDE RESPECTIVELY.

TOLERANCES UNLESS SPEC DECIMAL X±.1 XX±.05 XXX± .030	ANGULAR	W.	TM VAL	6024 SILVER CREEK VALLEY ROAD. SAN JOSE, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572			
APPROVALS	DATE		TITLEND/NDG40 PACKAGE OUTLINE				
DRAWN Mæ	05/31/10		.0 x 5.0 mm BODY,E		3.50mr	n SQ.	
CHECKED		0	.40 mm PITCH QFN				
		SIZE	DRAWING No.			REV	
		С	PSC-429.	2-	02	00	
		DO NOT SCALE DRAWING			SHEET 1	OF 2	

	REVISIONS						
REV	DESCRIPTION	DATE	APPROVED				
00	INITIAL RELEASE	5/17/16	JH				



RECOMMENDED LAND PATTERN

NOTES:

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- 2. TOP DOWN VIEW AS VIEWED ON PCB.

- 3. COMPONENT OUTLINE SHOWS FOR REFERENCE IN GREEN.
 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED			72		ÆR CREEK OAD. SAN (JOSE,	
DECIMAL			TM VAI	95138		·	
	±1°	4		ONE: (4	108) 284-82	200	
XX±.05 XXX± .030		W	/ww.IDT.com FAX	X: (408) 284-3572	!	
APPROVALS	DATE		D/NDG40 PACKAGE (
DRAWN Mæ	05/31/10	5	5.0 x 5.0 mm BODY,EPAD 3.50mm SQ				
CHECKED		0	.40 mm PITCH QFN	1			
		SIZE	DRAWING No.			REV	
		C	PSC-429	2-	02	00	
		DO NO	T SCALE DRAWING		SHEET 2	OF 2	